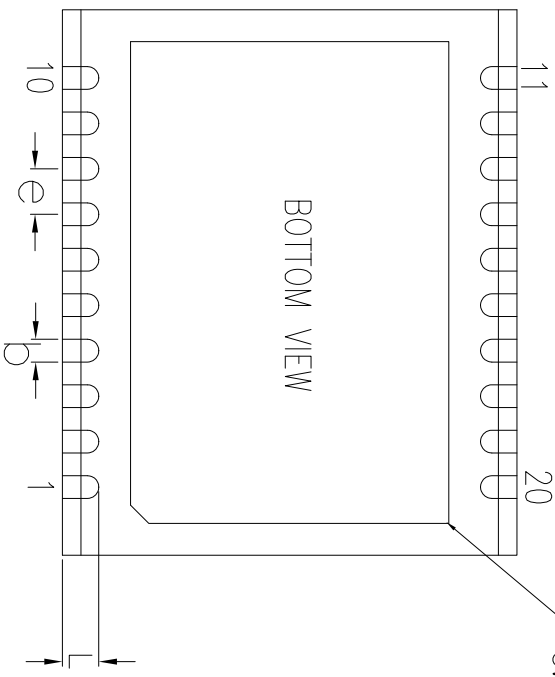
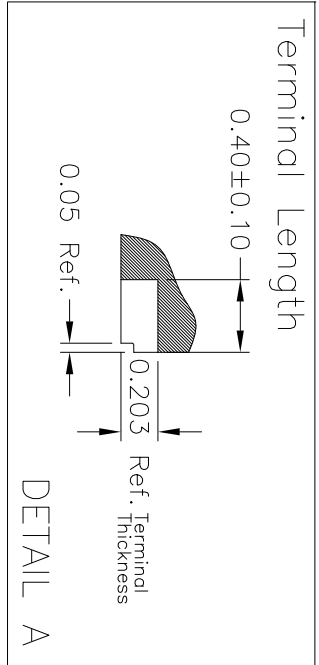
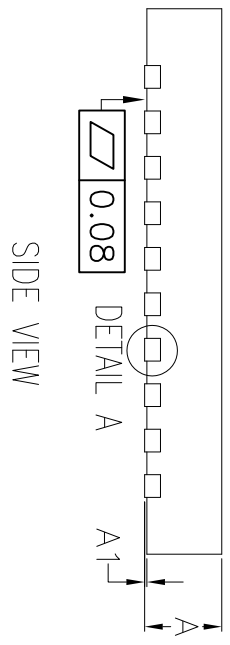
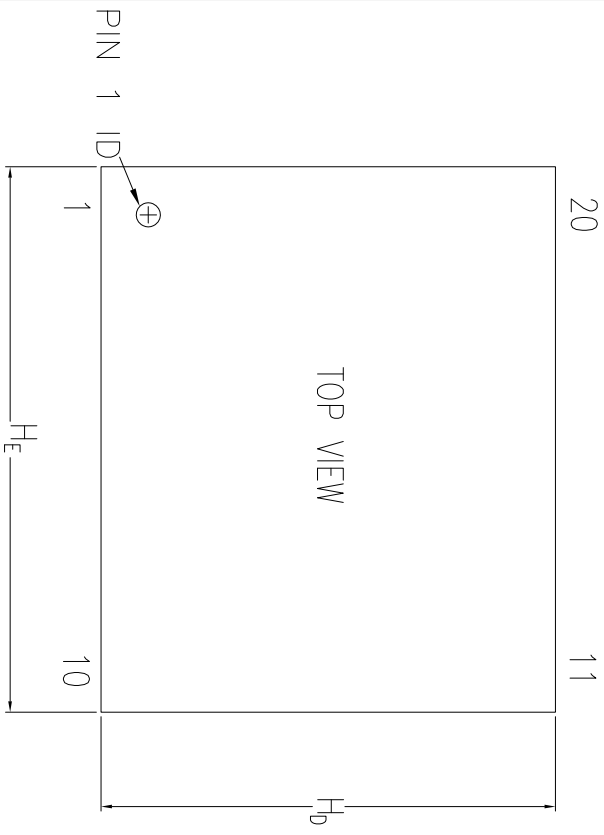


BASED ON JEDEC MO-229

1. DIMENSIONS (IN MILLIMETERS)



EXPOSED PAD
5.3 x 3.5

- 2. WEIGHT $\leq 0.05g$
- 3. PACKAGE BODY MATERIAL LOW STRESS EPOXY
- 4. LEAD MATERIAL Cu ALLOY
- 5. LEAD FINISH SOLDER PLATING

DIMENSIONS	MIN.	MAX.
A	0.8	0.9
A1	0	0.05
b	0.2	0.3
e	0.5 nom	
Hd	4.9	5.1
He	5.9	6.1
L	0.3	0.5

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	2/12/16	J.HUA

TOLERANCES UNLESS SPECIFIED		APPROVALS	
DECIMAL	ANGULAR	DATE	
xxx±	±	2/12/16	
xxxx±			
xxxx±			
www.IDT.com		TITLE NUG20 PACKAGE OUTLINE	
6024 Silver Creek Valley Rd San Jose, CA 95138 PHONE: (408) 727-6116 FAX: (408) 492-8874		6.0 x 5.0 mm BODY, EPAD 5.3 x 3.5 0.5 mm PITCH DFN	
DRWNG	DRG	SIZE	REV
024G		C	00
CHECKED		DRAWING No.	
		PSC-4643	
DO NOT SCALE DRAWING		SHEET 1 OF 1	